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Nota di contenuto	MONDAY, OCTOBER 29, 2001 -- SESSION I - KEYNOTE -- A Future View of Server Systems (Keynote) 3 (4) -- SESSION II - LOW POWER -- Architectural Approaches to Reducing Power Rtem Costs (Invited Paper) 7 (2) -- ``Watts'' the Matter: Power Reduction Issues (Invited Paper) 9 (2) -- Digital Signal Processors (DSPs) for Low Power Consumption Wireless Applications (Invited Paper) 11 (6) -- SESSION III - RF/MICROWAVE -- Characterization of the Novel Anisotropic Uniplanar Compact Photonic Band-Gap Ground Plane (UC-PBG-GP) 17 (4) -- Measuring Radiation of Small Electronic Equipment in Three-Dimensional TEM Cells 21 (4) -- Effects of Decreasing Extent of Electromagnetic Field at LSI Mounting Area on Radiated Emission from PCB 25 (4) -- Millimeter Wave Package Design: A Comparison of Simulation and Measurement Results 29 (6) -- SESSION IV - TRANSMISSION LINE MODELING -- Recovering Lossy Multiconductor Transmission Line Parameters From Impedance or Scattering Representations 35 (4) -- The Effects of Via Transitions on Differential Signals 39 (4) -- Analysis of Transmission Line Circuits Using Multi-Dimensional Model Reduction Techniques (Student Paper) 43 (4) -- Prime: Passive Realization of Interconnect Models from Measured Data 47 (4) -- Time-Domain Scattering Method Using Triangle Impulse Responses for Modeling Electronic Packaging Components 51 (4) -- Analysis of Transmission Line Structures Using a Dynamic Analysis through WIPL-D 55 (6) -- SESSION V - OPEN FORUM (POSTERS) AND RECEPTION -- Power Distribution -- Reducing Power Bus Impedance at Resonance with